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(54) Title: POST CMP CLEANING COMPOSITIONS

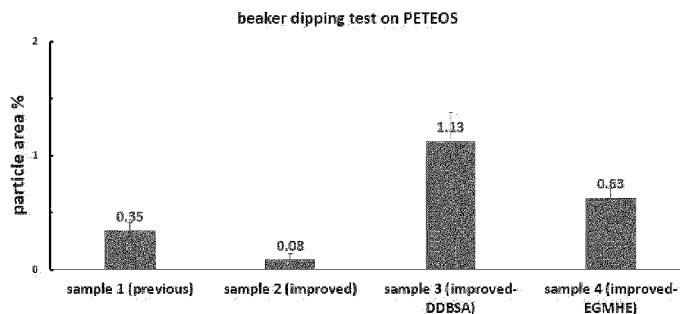


Figure 1

(57) Abstract: In general, the invention provides high pH cleaning compositions for dielectric surfaces such as PETEOS, SiO<sub>2</sub>, thermal oxide, silicon nitride, silicon, etc. The compositions of the invention afford superior surface wetting, dispersion of particles and organic residues, and prevents redeposition and re-agglomeration of the dispersed residue during cleaning to afford superior cleaning and low defectivity.



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